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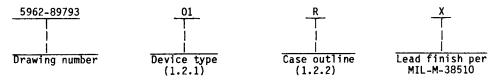
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

#### SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54ACT520	8-bit identity comparator, TTL compatible inputs
02	54ACT521	8-bit identity comparator, TTL compatible inputs
03	54ACT11520	8-bit identity comparator, TTL compatible inputs
04	54ACT11521	8-bit identity comparator, TTL compatible inputs

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in appendix C of MIL-M-38510, and as follows:

## Outline letter Case outline

R	D-8 (20-lead, $1.060$ " x $.310$ " x $.200$ "), dual-in-line package
S	F-9 (20-lead, .540" x .300" x .100"), flat package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings.

```
DC input voltage range (V_{IN}) \underline{1}/ -----
                                             -0.5 V dc to V_{\rm CC} + 0.5 V dc
DC output voltage range (V_{OUT}) \underline{1}/ - - - -
                                             -0.5 V dc to V_{CC} + 0.5 V dc
DC input diode current (I_{IK}) - - - - - -
                                             ±20 mA
DC output diode current (per pin) (I_{OK}) --
                                             ±50 mA
DC V<sub>CC</sub> or GND current -----
                                             ±100 mA
Storage temperature range - - - - - - -
                                             -65°C to +150°C
Maximum power dissipation (P_D) - - - - - -
                                             500 mW
Lead temperature (soldering, 10 seconds) - -
                                             +300°C
Thermal resistance, junction-to-case (\theta_{JC}) -
                                             See MIL-M-38510, appendix C
Junction temperature (T_{\rm J}) \underline{2}/ - - - - - -
```

Unless otherwise specified, all voltages are referenced to ground.
Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions in accordance with method 5004 of MIL-STD-883.

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# 1.4 Recommended operating conditions.

```
Supply voltage range (V_{CC}) ----- +4.5 V dc to +5.5 V dc Input voltage range ----- 0.0 V dc to V_{CC} Output voltage range ----- 0.0 V dc to V_{CC} Case operating temperature range (T_C) -- -55°C to +125°C Input rise or fall time: (t_r, t_f):

V_{CC} = 4.5 V, 5.5 V ----- 8 ns/V
```

#### 2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

**STANDARD** 

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

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- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2  $\underline{\text{Truth table}}$ . The truth table shall be as specified on figure 2.
  - 3.2.3 Logic diagrams. The logic diagrams shall be as specified on figure 3.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review.</u> DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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Test	Symbol	Condit   -55°C < T <sub>C</sub>  unless otherwis	< +125°C 1/	Device	Group A subgroups	   Lim         Min	nits Max	Unit T
High level output	v <sub>OH</sub>	V <sub>71</sub> - 0.8 V	V <sub>CC</sub> = 4.5 V	A11	1, 2, 3	4.4		V
vol tage		VIH = 2.0 V, I OH = -50 μA	V <sub>CC</sub> = 5.5 V			5.4		j   
	j 	V <sub>IL</sub> = 0.8 V,   V <sub>IH</sub> = 2.0 V,   I <sub>OH</sub> = -24 mA	V <sub>CC</sub> = 4.5 V	i i	 	3.7		
	 	$I_{OH}^{1H} = -24 \text{ mÅ}$	V <sub>CC</sub> = 5.5 V			4.7		
		V <sub>IL</sub> = 0.8 V, V <sub>IH</sub> = 2.0 V, I <sub>OH</sub> = -50 mA	V <sub>CC</sub> = 5.5 V			3.85		
Low level output	ı v <sub>oL</sub>	V <sub>IL</sub> = 0.8 V,	V <sub>CC</sub> = 4.5 V	A11	1, 2, 3	i i	0.1	V
voltage	i i	$V_{IH}^{1L} = 2.0 \text{ V},$ $I_{OL} = 50  \mu\text{A}$	V <sub>CC</sub> = 5.5 V				0.1	       
	<u> </u> 	V <sub>IL</sub> = 0.8 V,   V <sub>IH</sub> = 2.0 V,	V <sub>CC</sub> = 4.5 V			 	   0.5 	
		I I OL = 24 mA	V <sub>CC</sub> = 5.5 V				0.5	 
		VIL = 0.8 V, VIH = 2.0 V, IOL = 50 mA	V <sub>CC</sub> = 5.5 V		 		1       1.65 	         
High level input voltage	V <sub>IH</sub>	2/	V <sub>CC</sub> = 4.5 V	A11	1, 2, 3	2.0		V
<b>3</b>			V <sub>CC</sub> = 5.5 V	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		2.0	   	   
Low level input voltage	A <sup>IF</sup>	2/	V <sub>CC</sub> = 4.5 V	All	     1, 2, 3		0.8	v
	   	1	V <sub>CC</sub> = 5.5 V	,	 		0.8	
See footnotes at en			SIZE		1	<del>, , , , , , , , , , , , , , , , , , , </del>		
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Took	C.mr.b.=1	_				10	0	T		1
Test	Symbol   	-55°C <	ondition T <sub>C</sub> <u>&lt;</u> +1 otherwis	s 25°C <u>1</u> / e specif	ied	Device    type 	Group A subgroups		T	Uni   
Input leakage current	IIL1	V <sub>IN</sub> = 0.0		V <sub>CC</sub> = 5		01,03	1, 2, 3		-1.0	mA
B inputs	I <sub>IH1</sub>	   V <sub>IN</sub> = 5.5	٧	† 		02,04		<del> </del>	-1.0	ļμA
				!		01,03		<del> </del>	10.0	1
Input leakage	II <sub>IL2</sub>	   V <sub>IN</sub> = 0.0	v	  V <sub>CC</sub> = 5	5 V	02,04	1, 2, 3	-	1.0	<u>μ</u> β
current, other	1.117		<del></del>	T T	• • •	02,04	1, 2, 3	<del>                                     </del>	-1.0	T
,	I IH2	V <sub>IN</sub> = 5.5	٧	<u> </u> 	•	01,03		1	+1.0	
	ļ					02,04		<u> </u>	1.0	ļμA
Maximum I <sub>CC</sub> /TTL inputs high	delta  I <sub>CC</sub>	VCC = 5.5     One input     Other inpu	V, at 3.4 V ts at GN	, D or V <sub>CC</sub>		A11	1, 2, 3	     	     1.6 	   mA 
Quiescent current	Icc	V <sub>IN</sub> = V <sub>CC</sub> (	or GND V			  01,02,   04	1, 2, 3		  160 	μΑ     
Quiescent current	ICC	   B inputs at	t GND	Other in Section 1975   1975		03	1, 2, 3		8.0	mA
		   B inputs op 	oen	V <sub>CC</sub> = 5	.5 V	03			  160   	μA
Input capacitance	CIN	See 4.3.1c				All	4		10	pF
Power dissipation capacitance	C <sub>PD</sub>	See 4.3.1c	<u>3</u> /			   A11   	4		   60 	   
Functional tests		Tested at N repeated at 4.3.1d	/ <sub>CC</sub> = 4.9	5 V and 5.5 V, se	ee	A11   	7, 8		]   	
Propagation delay time, An or Bn to U <sub>A</sub> =B	t <sub>PHL1</sub>	V <sub>CC</sub> = 4.5 \ C <sub>L</sub> = 50 pF R <sub>L</sub> = 500Ω			-	01,02	9 10,11	1.5	11.0 12.5 12.4	1
^	1	See figure	4		-	03,04	10, 11	1.5	14.8	
	t <sub>PLH1</sub>	!				01,02   	9 10, 11	1.5	12.0	! !
						03,04	9 10, 11	11.5	13.0	
ee footnotes at end	of table									
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Test	Symbol	Conditions	Device		Lir	nits	Unit
		-55°C < T <sub>C</sub> < +125°C <u>1/</u>   unless otherwise specified	type	subgroups	Min	Max	
ropagation delay	tpHL2	V <sub>CC</sub> = 4.5 V 4/  C <sub>I</sub> = 50 pF	01,02	9 10, 11	1.5	8.5 9.0	ns
to $\overline{0}_{A=B}$		$ R_L  = 500\Omega$  See figure 4	03,04	9 10, 11	1.5	9.0	
	t <sub>PLH2</sub>	-	01,02	9	1.5	8.5 8.5	
			03,04	9	1.5	9.3	İ

1/ V<sub>OH</sub> and V<sub>OL</sub> will be tested at V<sub>CC</sub> = 4.5 V. V<sub>OH</sub> and V<sub>OL</sub> are guaranteed, if not tested, for V<sub>CC</sub> = 5.5 V. Limits shown apply to operation at V<sub>CC</sub> = 5.0 V ± 0.5 V. Transmission driving tests are performed at V<sub>CC</sub> = 5.5 V with a 2 ms duration maximum.
2/ The V<sub>IH</sub> and V<sub>IL</sub> tests are not required, and shall be applied as forcing functions for the V<sub>OL</sub> on V<sub>CC</sub> = 5.5 V.

 $V_{OH}$  or  $V_{OL}$  tests. Power dissipation capacitance (CpD), determines the dynamic power consumption,  $P_D$  = (CpD + CL)( $V_{CC} \times V_{CC}$ ) f +  $I_{CC}$  ( $V_{CC}$ ), and dynamic current consumption ( $I_S$ ) is,  $I_S$ 

= (Cpp + CL) VCC f + ICC. Are equal to limits at  $V_{CC}$  = 4.5 V and are guaranteed by testing at  $V_{CC}$  = 4.5 V. Minimum ac limits are guaranteed for  $V_{CC}$  = 5.5 V by guardbanding  $V_{CC} = 4.5 \text{ V limits to 1.5 ns (minimum)}$ .

- 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
    - (2)  $T_A = +125$ °C, minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method  $\frac{5005}{6}$  of MIL-SID-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

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Device types	01 and 02	03	and 04	٦
  Case outlines	R, S, 2	l R	2	7
Terminal number	   Terminal   symbol		 	T   
1	T <sub>A=B</sub>	B1	I В3	I
2	A0	A1	A3	!
3	B0	В0	B2	
4	A1	A0	A2	1
5	B1	I GNID	T <sub>A≃B</sub>	
6	A2	Ō <sub>A=B</sub>	B1	ļ
7	В2	B7	A1	
8	<b>A</b> 3	A7	l BO	1
9	В3	B6	A0	
10	GND	I A6	GND	
11	A4	l   85	O <sub>A=B</sub>	
12	B <b>4</b>	A5	B7	ļ
13	A5	В4	A7	ļ
14	B5	A4	В6	
15	A6	V <sub>CC</sub>	<b>A</b> 6	!
16	В6	В3	B5	!
17	A7	A3	<b>A</b> 5	
18	В7	B2	B <b>4</b>	
19	ō <sub>A=B</sub>	A2	A4	
20	v <sub>cc</sub>	T <sub>A=B</sub>	Vcc	

A0 - A7 = Word A inputs

 $\begin{array}{ll} B0 - B7 = \text{Word } A \text{ inputs} \\ \overline{I}_{A=B} = \text{Expansion or enable inputs} \\ \overline{U}_{A=B} = \text{Identity output} \end{array}$ 

FIGURE 1. Terminal connections.

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Device types 01, 02, 03, and 04

Inp	Inputs						
Ī <sub><b>A</b>=B</sub>	A, B	Ō <sub>A=B</sub>					
   L	A = B*	L					
L	A≠B	н					
н	A = B*	н					
Н	A≠B	! н ј					

H = High voltage level L = Low voltage level \* = AO = BO, A1 = B1, A2 = B2, ..., A7 = B7

FIGURE 2. Truth table.

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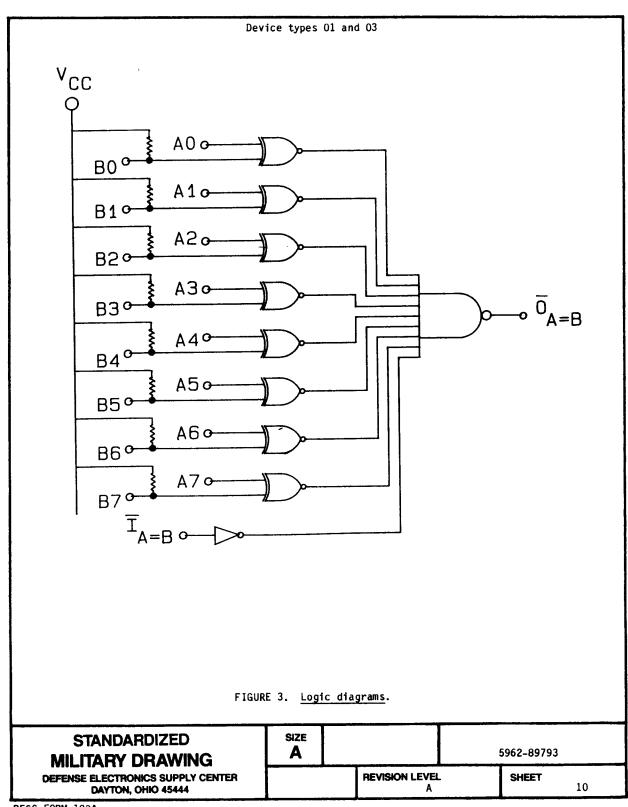
SIZE Α REVISION LEVEL

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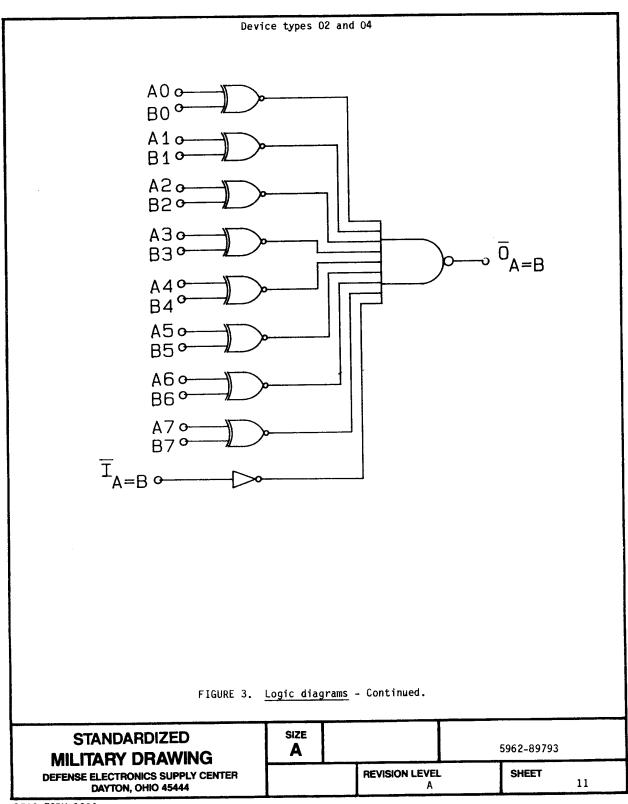
SHEET 9

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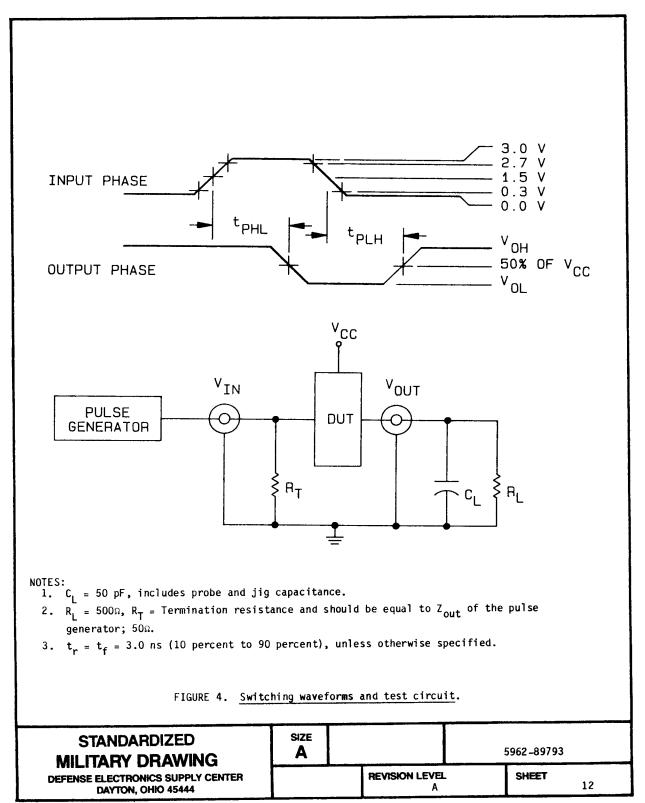
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## TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups     (per method     5005, table I)
  Interim electrical parameters   (method 5004)	
	1*, 2, 3, 7, 8, 9
Group A test requirements   (method 5005)	1, 2, 3, 4, 7, 1 8, 9, 10, 11
  Groups C and D end-point   electrical parameters   (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1.

## 4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 ( $C_{IN}$  and  $C_{PD}$  measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Capacitance shall be measured between the designated terminal and GND at a frequency of 1 MHz. Test all applicable pins on five devices with zero failures.
- d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2.

## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
  - (2)  $T_A = +125$ °C, minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

#### 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

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#### 6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6022.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone (513) 296-5375.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS.

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